MATERIALS FOR POWER DEVICES

InFORMS®

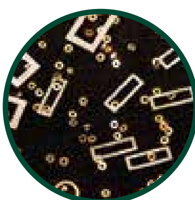
- Adds handling capabilities to soft and ductile indium and solder alloys
- Increases tensile and compressive strength
- Retains the unique attributes of the metals selected for the outer layer
- Designed to ensure predictable and level stand-off height
- Environmentally friendly

LV1000 Flux Coating

- Specifically designed for reducing voids in bottom termination components
- Passes Telcordia (Bellcore) testing in inactive state
- Durable for pick and place equipment
- High volume tape & reel packaging
- Consistent level coating as low as 0.5% by weight

Heat-Spring® Thermal Interface Materials

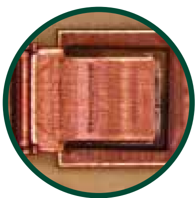
- Organic residue-free
- No pump out or bake out
- Thermal conductivity: up to 86W/mK for pure indium
- Tape & reel and tray packs available



Gold-Based Solder Alloys

Usage: High-melting (280°C and higher) and high-reliability with high tensile strength

- Available as solder pastes and preforms
- Preforms in specialized packaging for high UPH automated assembly
- Alloy variety tailored to specific high-reliability needs



NC-SMQ®75

- "Power-Safe" solder paste for die-attach
- Does not require cleaning
- Residue compatible with overmolding compounds
- Print and dispense versions available

Contact our experts today: asiapac@indium.com
Learn more: www.indium.com

From One Engineer To Another®

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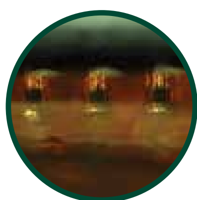
Form No. 99220 (A4) R1

MATERIALS FOR POWER SEMICONDUCTORS

A variety of materials is needed for the manufacturing of power devices. Indium Corporation provides both customer-proven and next-generation materials to meet the challenges of function, reliability, and increasingly complex customer compliance requirements.

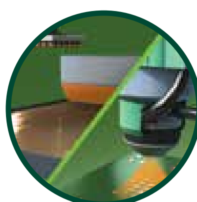
From semiconductor packaging and advanced assembly materials to engineered solder materials, let us find a solution to meet your needs.



Ultra-Low Residue No-Clean Flip-Chip Flux

Usage: No-clean flip-chip on leadframe (FCOL) for analog devices

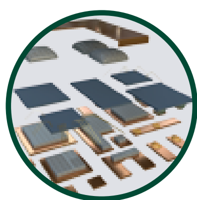
- Eliminates cost of cleaning
- Customer-proven compatibility with standard underfills and overmolding materials



Flip-Chip on Leadframe (FCOL) Solder Paste

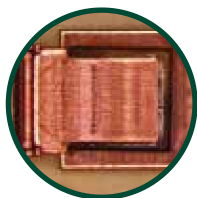
Usage: For fine-pitch (<150 micron) analog copper-pillar FCOL applications

- Consistent deposit volume
- Printing without excessive slump and bridging
- Flux compatible with high-Pb and other high-melting alloys



BiAgX® High-Temperature Pb-Free Solder Paste

- Drop-in replacement for high-Pb solder paste
- Pb- and Sb-free
- Used for high-melting (>260°C) solder joints
- Printing and dispensing paste available
- Winner of 2014 Global Technology Award in solder paste category



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